ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-	C. Bannock	burn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration en	n of the su	bstances v all lower	vithin the manufactu level materials for v	rer listed in the rest of the	item. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information														
Company name* Company unique ID			que ID		Unique ID Authority Response Date*									
nsemi										2023-06	5-08			
Contact Name Title - Contact			et]	Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product En			iro Compliance			NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - R			entative	Phone - Representative* Email - Representative*			ative*							
Product-Env-Stewards Pro			ro Compliance	NA Product-Env-Stewards@onsemi.				wards@onsemi.co	m					
Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	ASX342 D0-DR	342ATSC00XPE VGA 1/4 CIS SOC R)C		2023-06-08		М	MY5		108.92	mg	Each	
Ianufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020			J-STD-020 MSL	Rating	Peak Proce	ss Body Te	mperature	e Max Time at Peal	c Tempera	ture Num	ber of Reflow Cyc	les		
SnAgCu	(CU Alloy		3		260		С	30	secoi	nds 3			
omments														
TTENTION: MSL 3 Rated item requires	Bake and I	Dry Pack (after	electrical test)											
or more information regarding material o	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	23.9	mg		Misc.	proprietary data		0.0908	mg
			Supplier	Silicon (Si)	7440-21-3		23.5726	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2366	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	29.3	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5421	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5421	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5421	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1544	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5421	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5421	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.4353	mg
Lid Attach	1.52	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.684	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.304	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.19	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0076	mg
			Supplier	Curative	Proprietary Data		0.0304	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.304	mg
Iold Compound-Black	8.1	mg		Phenolic Resin	proprietary data		1.215	mg
			Supplier	Oxirane	39817-09-9		1.215	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		0.243	mg
			Supplier	Carbon Black (C)	1333-86-4		0.081	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.184	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.162	mg
Solder Ball	24.55	mg	Supplier	Silver (Ag)	7440-22-4		0.7365	mg
			Supplier	Tin (Sn)	7440-31-5		23.6907	mg
			Supplier	Copper (Cu)	7440-50-8		0.1227	mg
Substrate and Solder Mask	19.1	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.2139	mg

			Supplier	Fiber Glass (SiO2)	65997-17-3	2.4754	mg
			Supplier	Zinc (Zn)	7440-66-6	0.0287	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	0.445	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.2139	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.1108	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0019	mg
			Supplier	Acetophenone Derivative	Proprietary Data	0.6666	mg
			Supplier	Carbon Black (C)	1333-86-4	0.1108	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.1108	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	2.292	mg
			В	Nickel (Ni)	7440-02-0	0.2693	mg
			Supplier	Gold (Au)	7440-57-5	0.0096	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	1.3351	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.2139	mg
			Supplier	Copper (Cu)	7440-50-8	7.1549	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	3.4475	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5	0.25	mg